



S2AF THRU S2MF

2.0 AMP SURFACE MOUNT SILICON RECTIFIERS

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * High surge current capability

MECHANICAL DATA

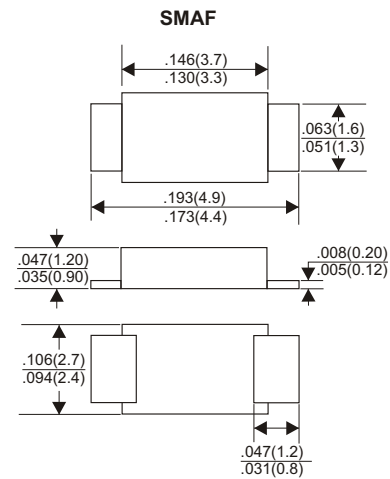
- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Terminals: Solder plated, solderable per MIL-STD-202F, method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

VOLTAGE RANGE

50 to 1000 Volts

CURRENT

2.0 Ampere



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Ta=100°C	2.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50							A
Maximum Instantaneous Forward Voltage at 2.0A	1.1							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=100°C	100							μA
Typical Junction Capacitance (Note 1)	60							pF
Typical Thermal Resistance R JA (Note 2)	47							°C/W
Operating and Storage Temperature Range Tj, Tstg	-55 — +150							°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance from Junction to Ambient.

RATING AND CHARACTERISTIC CURVES (S2AF THRU S2MF)

FIG.1-TYPICAL FORWARD

CHARACTERISTICS

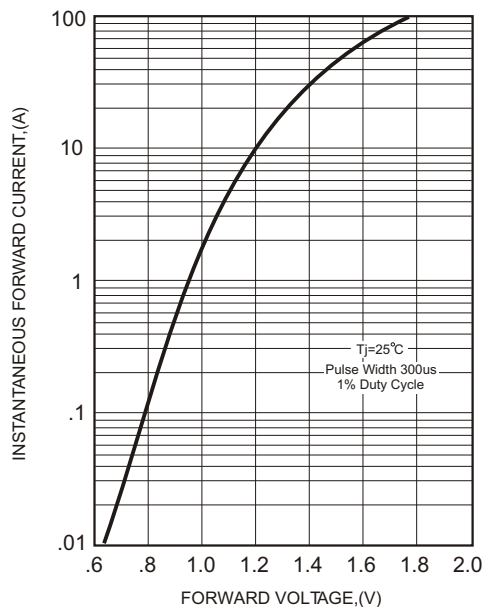


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

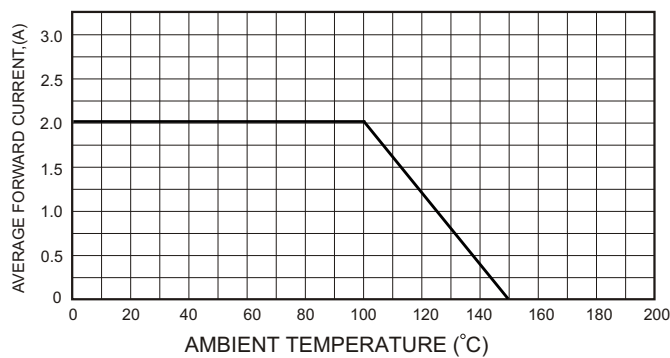


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

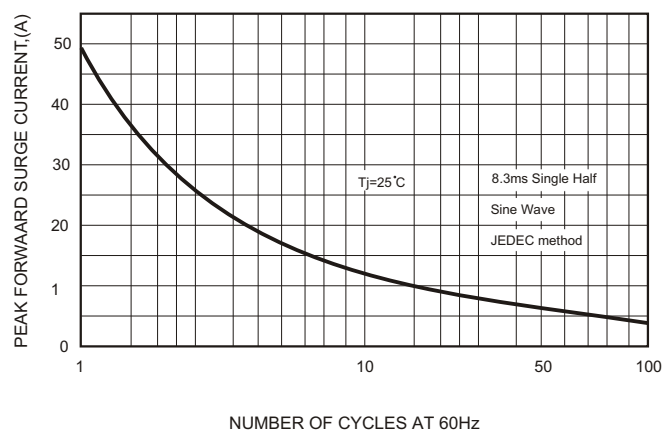


FIG.3 - TYPICAL REVERSE

CHARACTERISTICS

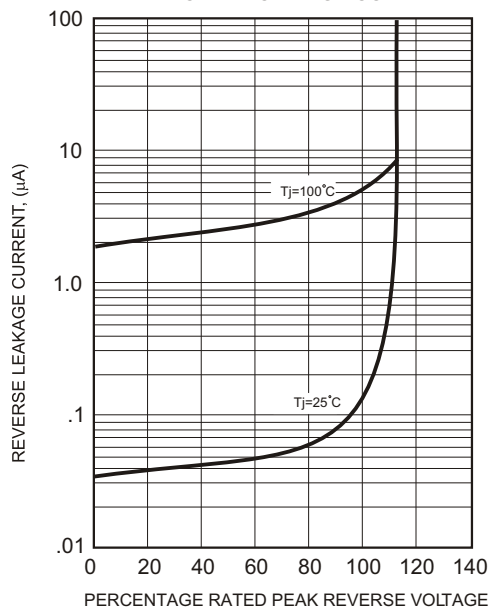
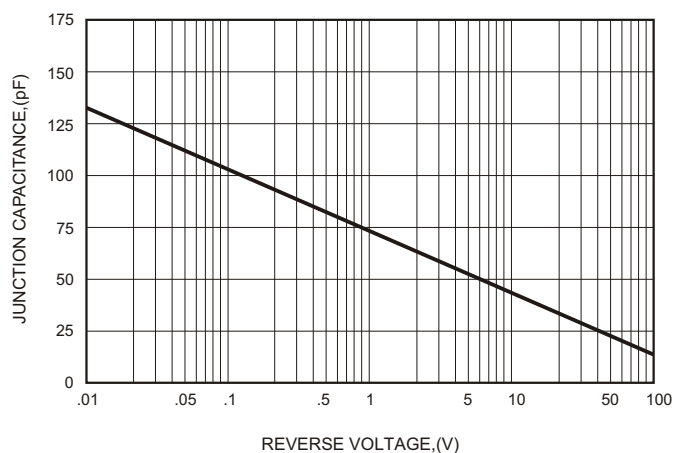


FIG.5-TYPICAL JUNCTION CAPACITANCE



Attention:

The graph is for reference only, can't be the basis for judgment.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement.